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74HC251; 74HCT251

8-input multiplexer; 3-state

Rev. 3 — 9 July 2013 Product data sheet

1. General description

The 74HC251; 74HCT251 is an 8-bit multiplexer with eight binary inputs (I0 to I7), three select inputs (S0 to S2) and an output enable input ($\overline{OE}$). The select inputs select one of the eight binary inputs and route it to the complementary outputs (Y and $\overline{Y}$). A HIGH on $\overline{OE}$ causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of V_{CC}.

2. Features and benefits

- Input levels:
  - For 74HC251: CMOS level
  - For 74HCT251: TTL level
- Low-power dissipation
- Non-inverting data path
- Specified in compliance with JEDEC standard no. 7A
- ESD protection:
  - HBM JESD22-A114F exceeds 2 000 V
  - MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from –40 °C to +85 °C and from –40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC251N	–40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT251N				
74HC251D	–40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT251D				
74HC251DB	–40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT251DB				
74HC251PW	–40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT251PW				

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4. Functional diagram

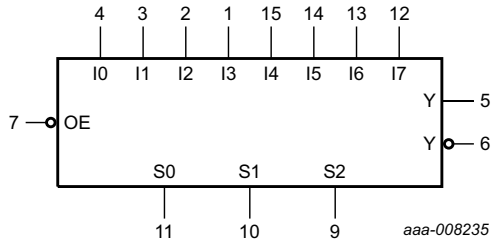

Fig 1. Logic symbol

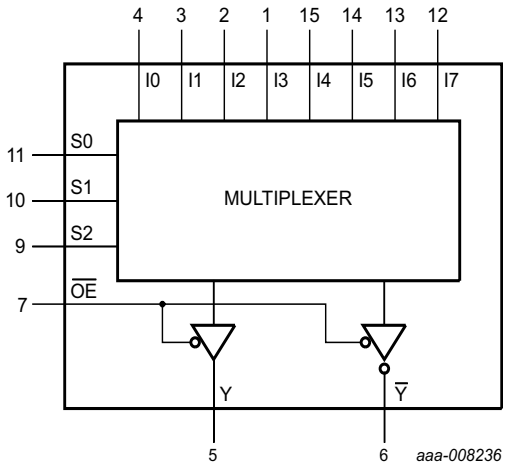

Fig 2. Functional diagram

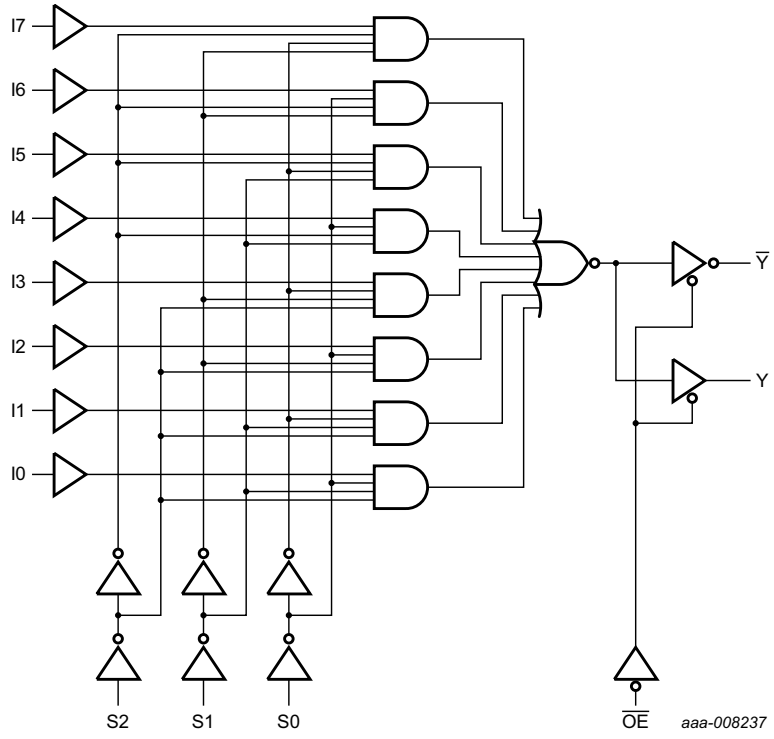

Fig 3. Logic diagram

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5. Pinning information

5.1 Pinning

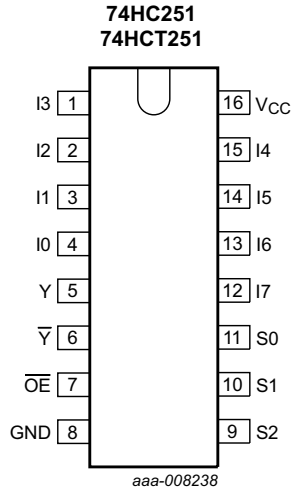

Fig 4. Pin configuration DIP16

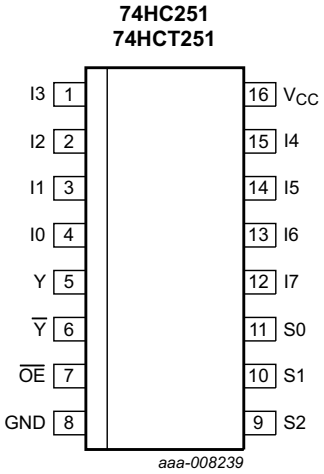

Fig 5. Pin configuration SO16

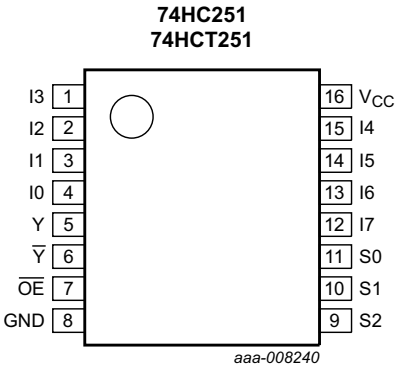

Fig 6. Pin configuration SSOP16 and TSSOP16

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
I0 to I7	4, 3, 2, 1, 15, 14, 13, 12	data inputs
Y	5	multiplexer output
$\overline{Y}$	6	complementary multiplexer output
$\overline{OE}$	7	output enable input (active LOW)
GND	8	ground (0 V)
S0, S1, S2	11, 10, 9	common data select inputs
V_{CC}	16	supply voltage

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6. Functional description

Table 3. Function table[1]

Input												Output	
$\overline{OE}$	S2	S1	S0	I0	I1	I2	I3	I4	I5	I6	I7	$\overline{Y}$	Y
H	X	X	X	X	X	X	X	X	X	X	X	Z	Z
L	L	L	L	L	X	X	X	X	X	X	X	H	L
L	L	L	L	H	X	X	X	X	X	X	X	L	H
L	L	L	H	X	L	X	X	X	X	X	X	H	L
L	L	L	H	X	H	X	X	X	X	X	X	L	H
L	L	H	L	X	X	L	X	X	X	X	X	H	L
L	L	H	L	X	X	H	X	X	X	X	X	L	H
L	L	H	H	X	X	X	L	X	X	X	X	H	L
L	L	H	H	X	X	X	H	X	X	X	X	L	H
L	H	L	L	X	X	X	X	L	X	X	X	H	L
L	H	L	L	X	X	X	X	H	X	X	X	L	H
L	H	L	H	X	X	X	X	X	L	X	X	H	L
L	H	L	H	X	X	X	X	X	H	X	X	L	H
L	H	H	L	X	X	X	X	X	X	L	X	H	L
L	H	H	L	X	X	X	X	X	X	H	X	L	H
L	H	H	H	X	X	X	X	X	X	X	L	H	L
L	H	H	H	X	X	X	X	X	X	X	H	L	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		–0.5	+7	V
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V	-	±20	mA
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	-	±20	mA
I_O	output current	$V_O = -0.5$ V to $(V_{CC} + 0.5$ V)	-	±25	mA
I_{CC}	supply current		-	+50	mA
I_{GND}	ground current		–50	-	mA
T_{stg}	storage temperature		–65	+150	°C

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Table 4. Limiting values *...continued*

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
P_{tot}	total power dissipation	T_{amb} = –40 °C to +125 °C				
	DIP16 package		[1]	-	750	mW
	SO16 package		[2]	-	500	mW
	(T)SSOP16 package		[3]	-	500	mW

[1] For DIP16 package: P_{tot} derates linearly with 12 mW/K above 70 °C.

[2] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.

[3] For SSOP16 and TSSOP16 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC251			74HCT251			Unit
			Min	Typ	Max	Min	Typ	Max	
V_{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V_I	input voltage		0	-	V_{CC}	0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T_{amb}	ambient temperature		–40	+25	+125	–40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V_{CC} = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V_{CC} = 6.0 V	-	-	83	-	-	-	ns/V

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9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T_{amb} = 25 °C			T_{amb} = –40 °C to +85 °C		T_{amb} = –40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC251										
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V_{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V_{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V_{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V_{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}								
		I_O = –20 μA; V_{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I_O = –20 μA; V_{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = –20 μA; V_{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I_O = –4.0 mA; V_{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I_O = –5.2 mA; V_{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}								
		I_O = 20 μA; V_{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 20 μA; V_{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 20 μA; V_{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 4.0 mA; V_{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I_O = 5.2 mA; V_{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I_{OZ}	OFF-state output current	V_I = V_{IH} or V_{IL}; V_O = V_{CC} or GND; V_{CC} = 6.0 V	-	-	±0.5	-	±5.0	-	±10.0	μA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 6.0 V	-	-	8.0	-	80	-	160	μA
C_I	input capacitance		-	3.5	-					pF

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Table 6. Static characteristics *...continued*

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T_{amb} = 25 °C			T_{amb} = –40 °C to +85 °C		T_{amb} = –40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HCT251										
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}; V_{CC} = 4.5 V								
		I_O = –20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = –4 mA	3.98	4.32	-	3.84	-	3.7	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}; V_{CC} = 4.5 V								
		I_O = 20 μA	-	0	0.1	-	0.1	-	0.1	V
		I_O = 4.0 mA	-	0.15	0.26	-	0.33	-	0.4	V
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I_{OZ}	OFF-state output current	V_I = V_{IH} or V_{IL}; V_{CC} = 5.5 V; V_O = V_{CC} or GND per input pin; other inputs at V_{CC} or GND; I_O = 0 A	-	-	±0.5	-	±5.0	-	±10	μA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	8.0	-	80	-	160	μA
ΔI_{CC}	additional supply current	V_I = V_{CC} – 2.1 V; other inputs at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V; I_O = 0 A								
		per input pin; In inputs	-	100	360	-	450	-	490	μA
		per input pin; $\overline{OE}$ input	-	150	540	-	675	-	735	μA
		per input pin; Sn input	-	150	540	-	675	-	735	μA
C_I	input capacitance		-	3.5	-					pF

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10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); C_L = 50 pF unless otherwise specified; for test circuit, see Figure 10.

Symbol	Parameter	Conditions		T_{amb} = 25 °C			T_{amb} = –40 °C to +85 °C		T_{amb} = –40 °C to +125 °C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
74HC251											
t_{pd}	propagation delay	In to Y; see Figure 7	[1]								
		V_{CC} = 2.0 V		-	50	170	-	215	-	255	ns
		V_{CC} = 4.5 V		-	18	34	-	43	-	51	ns
		V_{CC} = 5 V; C_L = 15 pF		-	15	-	-	-	-	-	ns
		V_{CC} = 6.0 V		-	14	29	-	37	-	43	ns
		In to $\overline{Y}$; see Figure 7	[1]								
		V_{CC} = 2.0 V		-	55	175	-	220	-	265	ns
		V_{CC} = 4.5 V		-	20	35	-	44	-	53	ns
		V_{CC} = 5 V; C_L = 15 pF		-	17	-	-	-	-	-	ns
		V_{CC} = 6.0 V		-	16	30	-	37	-	45	ns
		Sn to Y; see Figure 8	[1]								
		V_{CC} = 2.0 V		-	66	205	-	255	-	310	ns
		V_{CC} = 4.5 V		-	24	41	-	51	-	62	ns
		V_{CC} = 5 V; C_L = 15 pF		-	20	-	-	-	-	-	ns
		V_{CC} = 6.0 V		-	19	35	-	43	-	53	ns
		Sn to $\overline{Y}$; see Figure 8	[1]								
		V_{CC} = 2.0 V		-	69	205	-	255	-	310	ns
		V_{CC} = 4.5 V		-	25	41	-	51	-	62	ns
		V_{CC} = 5 V; C_L = 15 pF		-	21	-	-	-	-	-	ns
		V_{CC} = 6.0 V		-	20	35	-	43	-	53	ns
t_{en}	enable time	$\overline{OE}$ to Y, $\overline{Y}$; see Figure 8	[2]								
		V_{CC} = 2.0 V		-	36	140	-	175	-	210	ns
		V_{CC} = 4.5 V		-	13	28	-	35	-	42	ns
		V_{CC} = 6.0 V		-	10	24	-	30	-	36	ns
t_{dis}	disable time	$\overline{OE}$ to Y, $\overline{Y}$; see Figure 8	[3]								
		V_{CC} = 2.0 V		-	39	140	-	170	-	210	ns
		V_{CC} = 4.5 V		-	14	28	-	35	-	42	ns
		V_{CC} = 6.0 V		-	11	24	-	30	-	36	ns
t_t	transition time	Y, $\overline{Y}$; see Figure 7	[4]								
		V_{CC} = 2.0 V		-	19	75	-	95	-	110	ns
		V_{CC} = 4.5 V		-	7	15	-	19	-	22	ns
		V_{CC} = 6.0 V		-	6	13	-	16	-	19	ns
C_{PD}	power dissipation capacitance	C_L = 50 pF; f = 1 MHz; V_I = GND to V_{CC}	[5]	-	44	-	-	-	-	-	pF

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Table 7. Dynamic characteristics *...continued*

Voltages are referenced to GND (ground = 0 V); C_L = 50 pF unless otherwise specified; for test circuit, see Figure 10.

Symbol	Parameter	Conditions		T_{amb} = 25 °C			T_{amb} = –40 °C to +85 °C		T_{amb} = –40 °C to +125 °C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
74HCT251											
t_{pd}	propagation delay	In to Y; see Figure 7	[1]								
		V_{CC} = 4.5 V		-	22	35	-	44	-	53	ns
		V_{CC} = 5 V; C_L = 15 pF		-	19	-	-	-	-	-	ns
		In to $\overline{Y}$; see Figure 7	[1]								
		V_{CC} = 4.5 V		-	22	35	-	44	-	53	ns
		V_{CC} = 5 V; C_L = 15 pF		-	19	-	-	-	-	-	ns
		Sn to Y; see Figure 8	[1]								
		V_{CC} = 4.5 V		-	24	44	-	55	-	66	ns
		V_{CC} = 5 V; C_L = 15 pF		-	20	-	-	-	-	-	ns
		Sn to $\overline{Y}$; see Figure 8	[1]								
		V_{CC} = 4.5 V		-	25	44	-	55	-	66	ns
		V_{CC} = 5 V; C_L = 15 pF		-	21	-	-	-	-	-	ns
t_{en}	enable time	$\overline{OE}$ to Y, $\overline{Y}$; see Figure 8	[2]								
		V_{CC} = 4.5 V		-	13	28	-	35	-	42	ns
		V_{CC} = 5 V; C_L = 15 pF		-	13	-	-	-	-	-	ns
t_{dis}	disable time	$\overline{OE}$ to Y, $\overline{Y}$; see Figure 8	[3]								
		V_{CC} = 4.5 V		-	14	28	-	35	-	42	ns
		V_{CC} = 5 V; C_L = 15 pF		-	18	-	-	-	-	-	ns
t_t	transition time	Y, $\overline{Y}$; see Figure 7	[4]								
		V_{CC} = 4.5 V		-	7	15	-	19	-	22	ns
C_{PD}	power dissipation capacitance	C_L = 50 pF; f = 1 MHz; V_I = GND to V_{CC}	[5]	-	46	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.

[2] t_{en} is the same as t_{PZH} and t_{PZL}.

[3] t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[4] t_t is the same as t_{THL} and t_{TLH}.

[5] C_{PD} is used to determine the dynamic power dissipation (P_D in µW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in V;
N = number of inputs switching;
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

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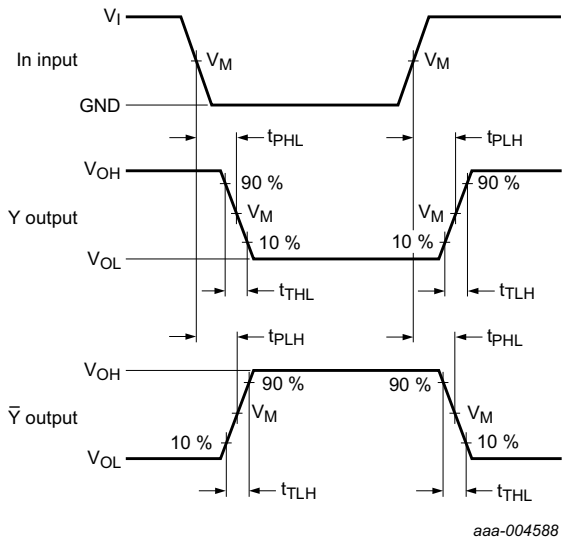
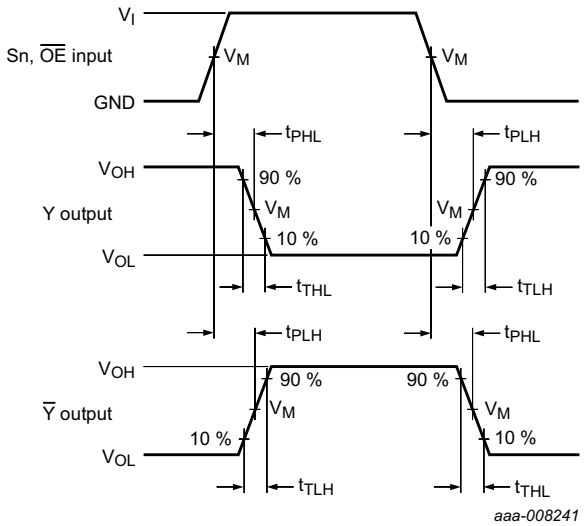
11. Waveforms



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 7. Propagation delay input (In) to output (Y, $\overline{Y}$) and the output (Y, $\overline{Y}$) transition time



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 8. Propagation delay input (Sn, $\overline{OE}$) to output (Y, $\overline{Y}$)

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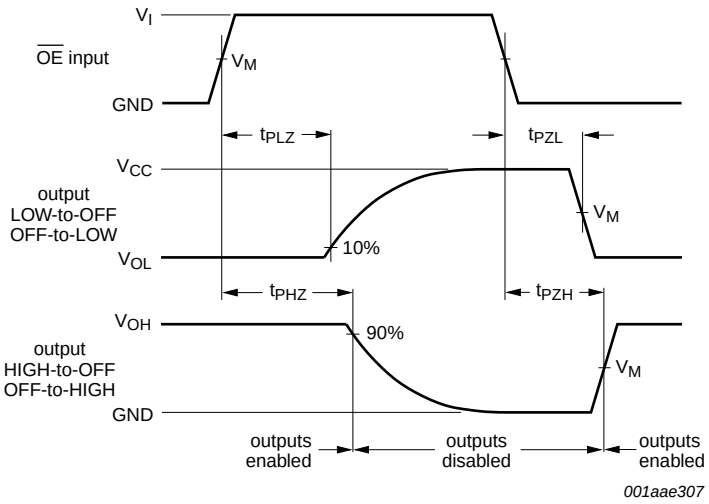

Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 9. Enable and disable times

Table 8. Measurement points

Type	Input	Output
	V_M	V_M
74HC251	$0.5V_{CC}$	$0.5V_{CC}$
74HCT251	1.3 V	1.3 V

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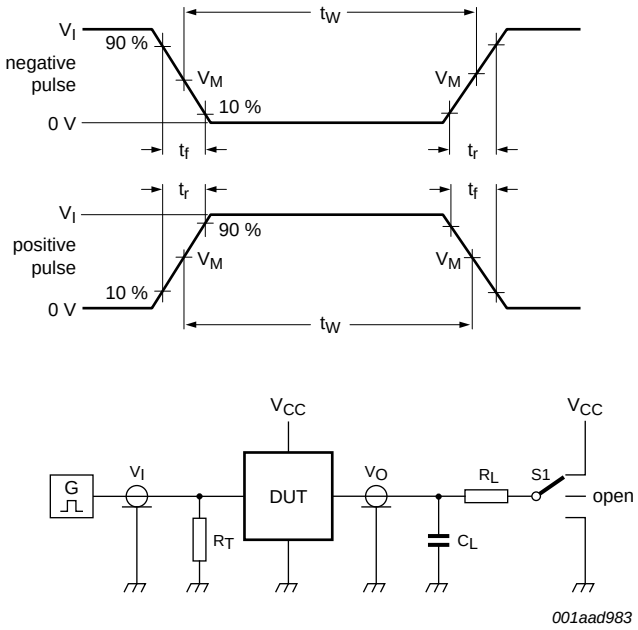

Test data is given in Table 9.

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig 10. Test circuit for measuring switching times

Table 9. Test data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC251	V_{CC}	6 ns	15 pF, 50 pF	1 kΩ	open	GND	V_{CC}
74HCT251	3 V	6 ns	15 pF, 50 pF	1 kΩ	open	GND	V_{CC}

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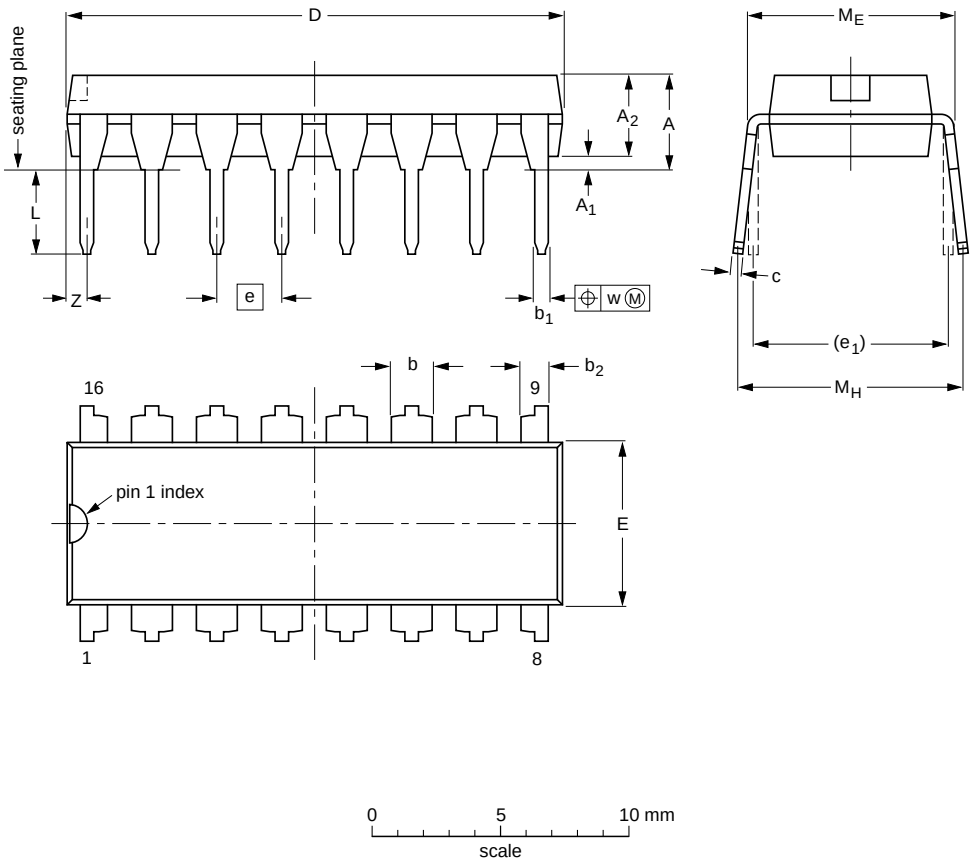
12. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil) **SOT38-4**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	b_2	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.02	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.03

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT38-4						~~95-01-14~~ 03-02-13

Fig 11. Package outline SOT38-4 (DIP16)

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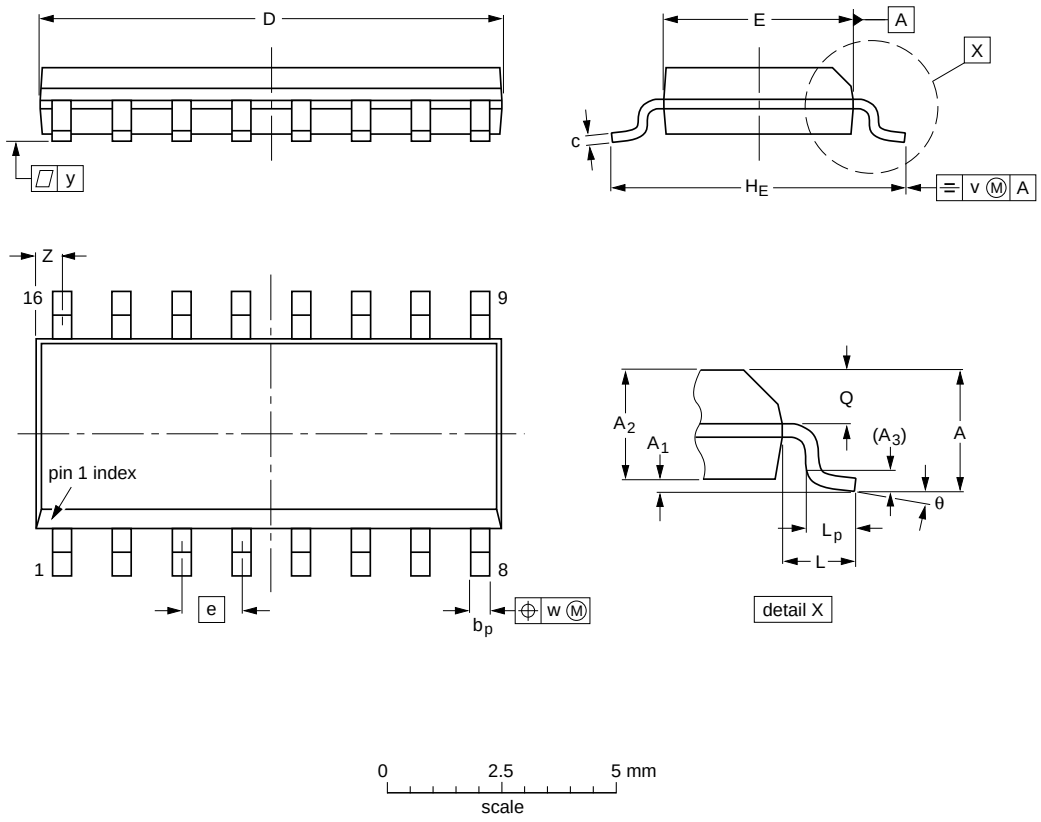
SO16: plastic small outline package; 16 leads; body width 3.9 mm **SOT109-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				~~99-12-27~~ 03-02-19

Fig 12. Package outline SOT109-1 (SO16)

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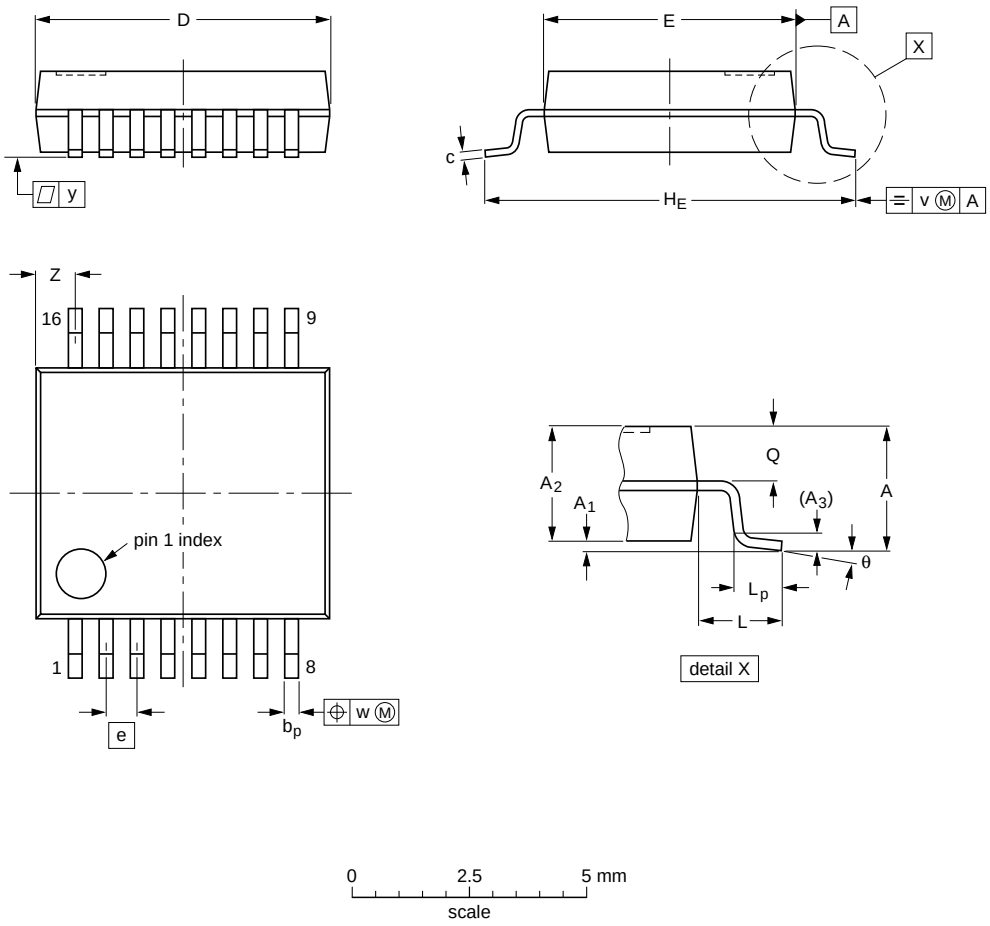
SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm **SOT338-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.00 0.55	8^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT338-1		MO-150				~~99-12-27~~ 03-02-19

Fig 13. Package outline SOT338-1 (SSOP16)

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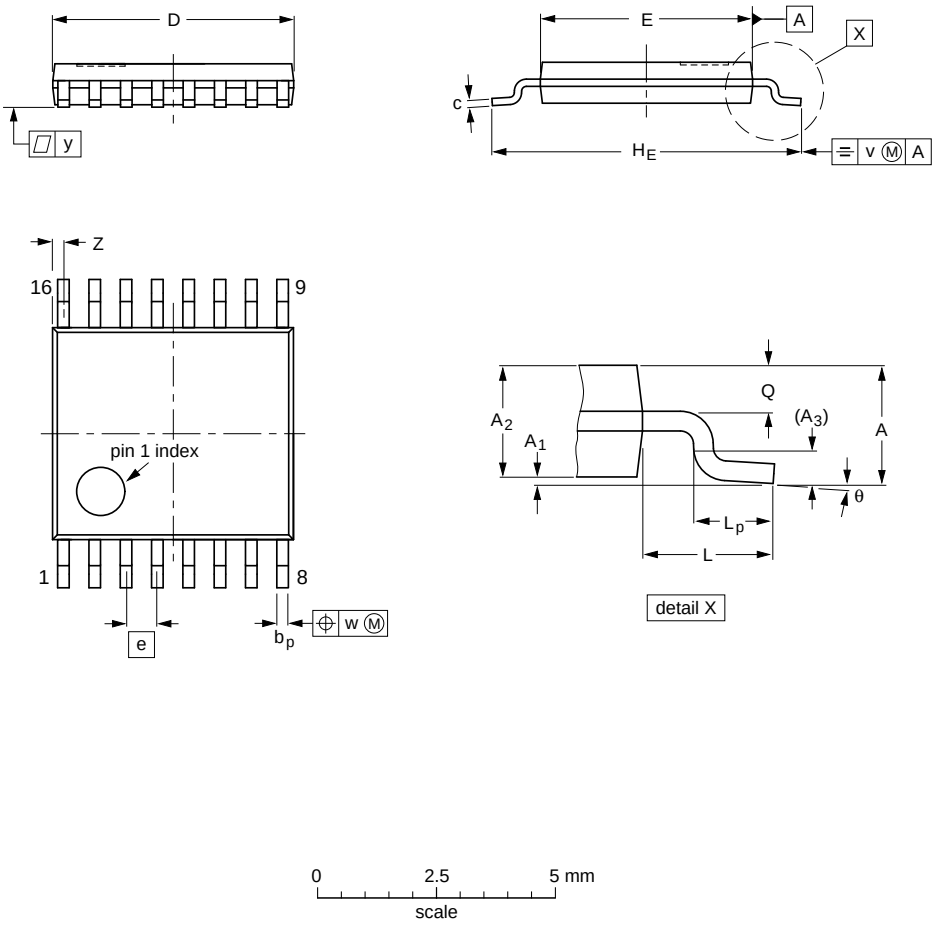
TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig 14. Package outline SOT403-1 (TSSOP16)

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13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic
MIL	Military

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT251 v.3	20130709	Product data sheet	-	74HC_HCT251_CNV v.2
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate.			
74HC_HCT251_CNV v.2	19970828	Product specification	-	

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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